Electronic Patent Application Fee Transmittal									
Application Number:	10677182								
Filing Date:	02-Oct-2003								
Title of Invention:	Method of forming solder resist pattern								
First Named Inventor/Applicant Name:	Jee-Soo Mok								
Filer:	Laura Cruz/Marivick Watson								
Attorney Docket Number:	LEPA121687								
Filed as Large Entity									
Utility Filing Fees									
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)				
Basic Filing:									
Pages:									
Claims:									
Miscellaneous-Filing:									
Petition:									
Patent-Appeals-and-Interference:									
Post-Allowance-and-Post-Issuance:									
Extension-of-Time:									

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)	
liscellaneous:					
Request for continued examination	1801	1	810	810	
	Tota	Total in USD (\$)			